

APPLICATION SPECIFICATION

1. SCOPE

This specification covers the requirements for application of the AMP* Modular Jack. These requirements are applicable to hand insertion tooling. For specific part numbers relative to the products covered in this specification see Figure 5.

2. NOMENCLATURE

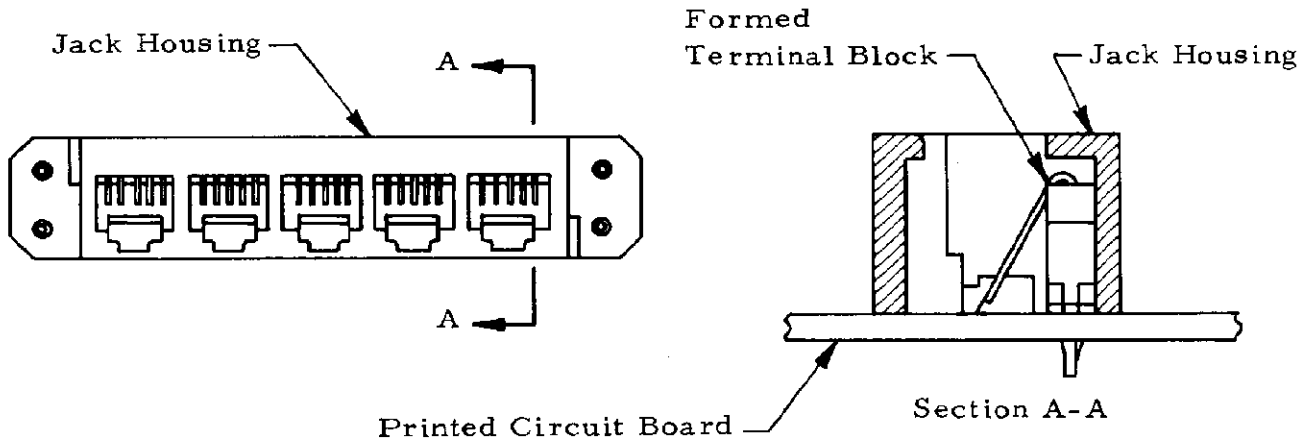


Figure 1

3. REQUIREMENTS

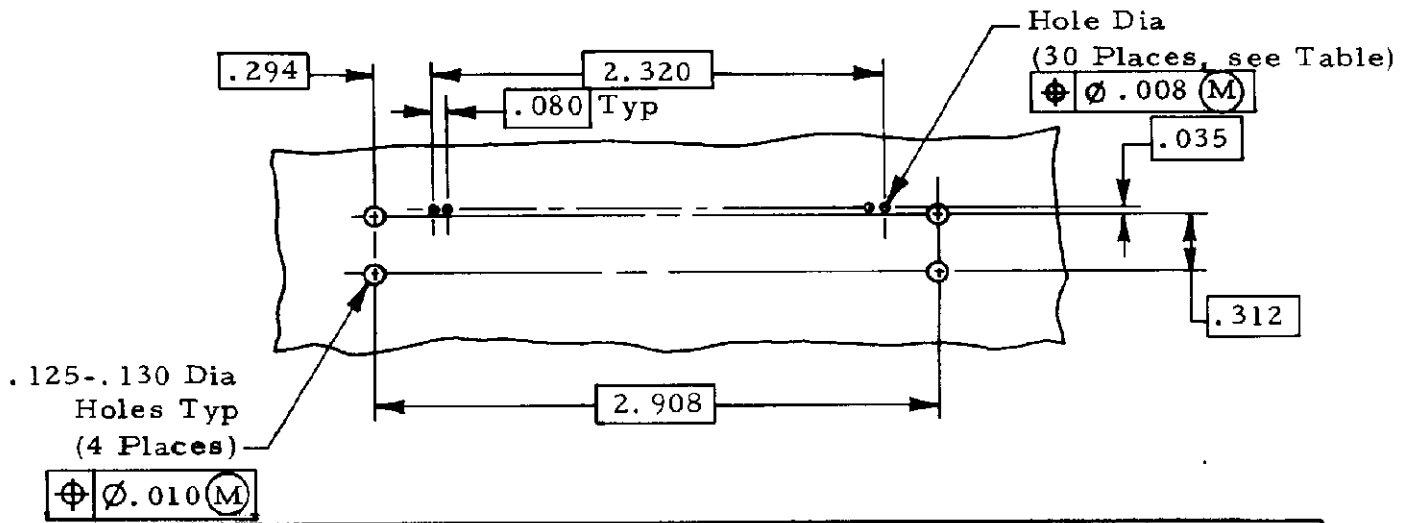
3.1. Printed Circuit Board

- A. Thickness shall be .062 nominal.
- B. Layout shall be as indicated in Figure 2.

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				CHK 5-7-82							
				APP <i>Jas Kilpatrick</i> 5/7/82	LOC B	A	NO 114-6009	REV 0			
				NAME SHEET 1 OF 3						JACK, MODULAR, APPLICATION OF	
DIST 06	LTR	REVISION RECORD	APP	DATE							



Hole Dia Before Plating	Plated Thru Hole Plating Thickness		Hole Dia After Reflow	Non-Plated Thru Hole Diameter
	Copper	Tin/Lead		
.037 - .039	.001 - .002	.0003 - .0012	.030 - .035	.032 - .034

Figure 2

3.2. Terminal Block Insertion

- A. Insert formed terminal block into printed circuit board, using insertion tool PN 231044-1, until post shoulders bottom on printed circuit board and align as indicated in Figure 3.

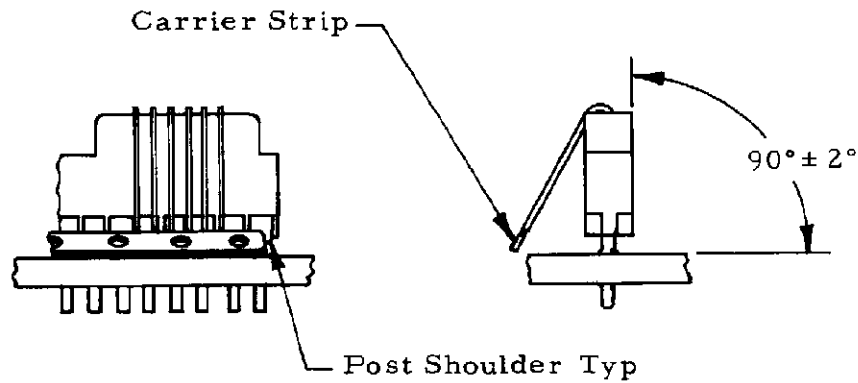


Figure 3

- B. Remove carrier strip by flexing back and forth.

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LOC B	NO A	114-6009		REV 0	
NAME JACK, MODULAR, APPLICATION OF					

3.3. Housing Assembly

Place housing over formed terminal block and secure with screws inserted from the underside of the printed circuit board into the housing as indicated in Figure 4.

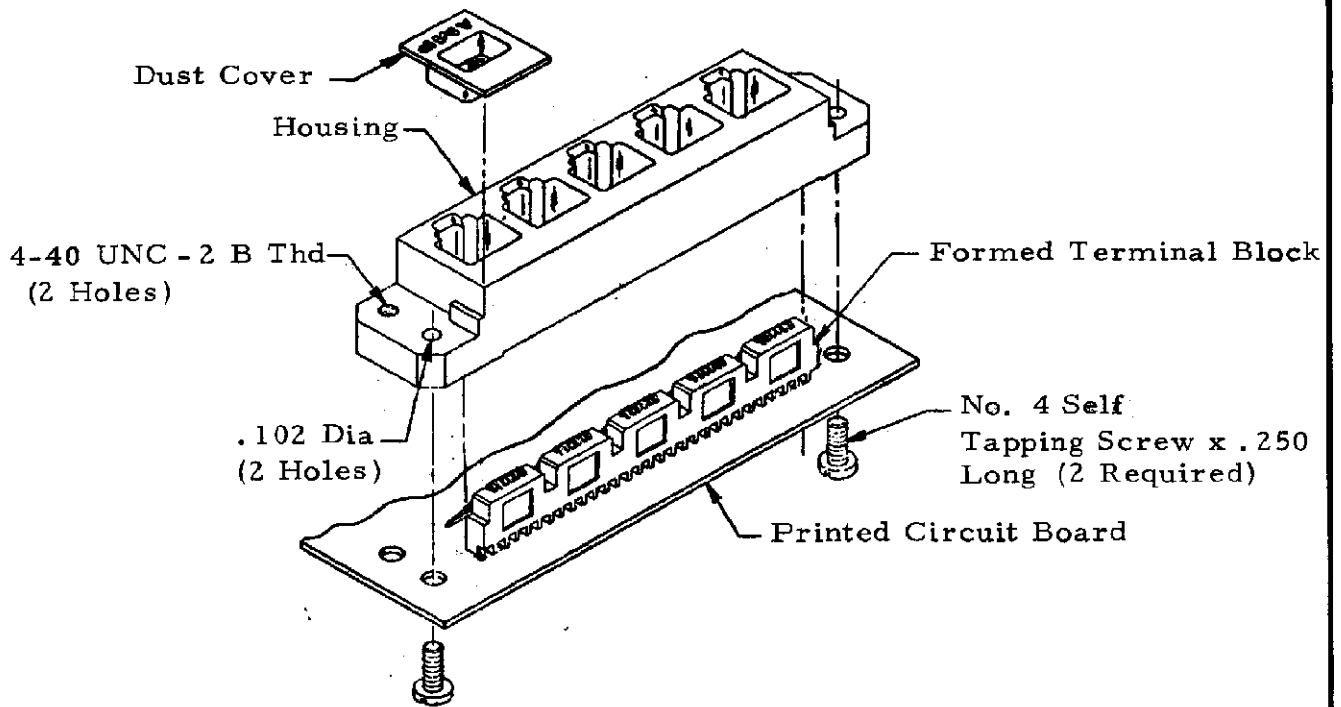


Figure 4

Description	Part Number
Dust Covers	553240-1
Housing	553156-2
Formed Terminal Block	553157-1

Figure 5

SHEET 3 OF 3	AMP AMP INCORPORATED Harrisburg, Pa.	
	LOC B	NO A
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		REV 0